Product Change Notification: DSNO-22DSCT552

Date:

28-Oct-2026

Product Category:

USB Port Power Controller

Notification Subject:

CCB 8245 Initial Notice: Qualification of Taiwan Semiconductor Manufacturing Corp (Fab 11) as new fabrication site for selected UCS1001-1, UCS1001-2, UCS1001-3, UCS1001-4, UCS1002-1, UCS1002-2, UCS1002-3, UCS1002-A, UCS1003-1, UCS1003-2, UCS1003-3, UCS2112, UCS2113, UCS2114, UCS81001, UCS81003 and UCS81002 device families available in 20L QFN (4x4x0.9mm), 20L VQFN (3x3x0.9mm) and 28L VQFN (5x5x0.9mm) packages.

Affected CPNs:

DSNO-22DSCT552_Affected_CPN_10282026.pdf
DSNO-22DSCT552_Affected_CPN_10282026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of Taiwan Semiconductor Manufacturing Corp (Fab 11) as new fabrication site for selected UCS1001-1, UCS1001-2, UCS1001-3, UCS1001-4, UCS1002-1, UCS1002-2, UCS1002-3, UCS1002-A, UCS1003-1, UCS1003-2, UCS1003-3, UCS2112, UCS2113, UCS2114, UCS81001, UCS81003 and UCS81002 device families available in 20L QFN (4x4x0.9mm), 20L VQFN (3x3x0.9mm) and 28L VQFN (5x5x0.9mm) packages.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)
Fabrication Site	Taiwan Semiconductor Manufacturing Corp. (Fab 5) (TC05)	Taiwan Semiconductor Manufacturing Corp. (Fab 11) (TC11)	Yes

	Pre Change	Post Change	Change (Yes/No)
Wafer Size	8"	8"	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying TC11 as a new fabrication site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: April 2027

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	October 2026					>	April 2027				
Work Week	40	41	42	43	44		14	15	16	17	18
Initial PCN Issue Date					x						
Qual Report Availability									x		
Final PCN Issue Date									x		

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: October 28, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-22DSCT552_Qual Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

DSNO-22DSCT552 - CCB 8245 Initial Notice: Qualification of Taiwan Semiconductor Manufacturing Corp (Fab 11) as new fabrication site for selected UCS1001-1, UCS1001-2, UCS1001-3, UCS1001-4, UCS1002-1, UCS1002-2, UCS1002-3, UCS1002-A, UCS1003-1, UCS1003-2, UCS1003-3, UCS2112, UCS2113, UCS2114, UCS81001, UCS81003 and UCS81002 device families available in 20L QFN (4x4x0.9mm), 20L

Affected Catalog Part Numbers (CPN):

UCS1001-3-BP-TR

UCS1001-4-BP

UCS1001-4-BP-TR

UCS1002-1-BP

UCS1002-1-BP-TR

UCS1002-2-BP

UCS1002-2-BP-TR

UCS1002-3-BP

UCS1002-3-BP-TR

UCS1002-A-BP-TR

UCS1003-1-BP

UCS1003-1-BP-TR

UCS1003-2-BP

UCS1003-2-BP-TR

UCS1003-3-BP

UCS1003-3-BP-TR

UCS2113T-2C-V/G4

UCS2113T-2C-V/G4VAO

UCS2113T-2-V/G4

UCS2114-1A-V/LX

UCS2114-1A-V/LXVAO

UCS2114-1-V/LX

UCS2114-1-V/LXVAO

UCS2114T-1-V/LX

UCS2114T-1-V/LXVAO

UCS2112-1-V/G4-V01

UCS2112-2-V/G4-V02

UCS2112T-1-V/G4-V01

UCS2112T-2-V/G4-V02

UCS81001AM-C1A-V01

UCS81003AM-C1A-V03

UCS81001AMR-C1A-V01

UCS81003AMR-C1A-V03

UCS81001AMR-C1A-V01-MB

UCS81002AM-C1A-V02

UCS1001-1-BP

UCS1001-1-BP-TR

UCS1001-2-BP

UCS1001-2-BP-TR

UCS1001-3-BP

UCS2112-1-V/G4

UCS2112-2-V/G4

UCS2112T-1-V/G4

UCS2112T-2-V/G4

UCS2113-1C-V/G4

UCS2113-1C-V/G4VAO

UCS2113-1-V/G4

UCS2113-2C-V/G4

UCS2113-2C-V/G4VAO

UCS2113-2-V/G4

UCS2113T-1C-V/G4

UCS2113T-1C-V/G4VAO

UCS2113T-1-V/G4

UCS2113T-1-V/G4VAO

UCS81002AMR-C1A-V02

QUALIFICATION PLAN SUMMARY

RELIABILITY LABORATORY

PCN #: DSNO-22DSCT552

Date:
June 16, 2026

Qualification of Taiwan Semiconductor Manufacturing Corp (Fab 11) as new fabrication site for selected UCS1001-1, UCS1001-2, UCS1001-3, UCS1001-4, UCS1002-1, UCS1002-2, UCS1002-3, UCS1002-A, UCS1003-1, UCS1003-2, UCS1003-3, UCS2112, UCS2113, UCS2114, UCS81001, UCS81003 and UCS81002 device families available in 20L QFN (4x4x0.9mm), 20L VQFN (3x3x0.9mm) and 28L VQFN (5x5x0.9mm) packages.

MICROCHIP

QUALIFICATION PLAN

Purpose: **Qualification of Taiwan Semiconductor Manufacturing Corp (Fab 11) as new fabrication site for selected UCS1001-1, UCS1001-2, UCS1001-3, UCS1001-4, UCS1002-1, UCS1002-2, UCS1002-3, UCS1002-A, UCS1003-1, UCS1003-2, UCS1003-3, UCS2112, UCS2113, UCS2114, UCS81001, UCS81003 and UCS81002 device families available in 20L QFN (4x4x0.9mm), 20L VQFN (3x3x0.9mm) and 28L VQFN (5x5x0.9mm) packages.**

CCB No.: **8245**

Test	Number of Lot/s	Sample Size (per lot)	Total Samples	Conditions
Pre-Conditioning (Precon)	3	77	231	0 fails at 25C, 125C Duration=48 hours
Early Life Failure Rate (ELFR)	3	800	2400	0 fails at 25C, 125C Duration=48 hours
High Temperature Operating Life (HTOL)	3	77	231	0 fails at 25C, -40C, 125C Duration=1008 Hours
Biased/Unbiased Highly Accelerated Reliability Testing (HAST/UHAST)	3	77	231	0 fails at Room to Hot
Temp Cycle (TC)	3	77	231	0 fails at Room to Hot
Power Temp Cycle (PTC)	1	45	45	0 fails at Room to Hot
Electrostatic Discharge -Human Body Model (ESD-HBM)	1	12	12	0 fails at Room and Hot

Test	Number of Lot/s	Sample Size (per lot)	Total Samples	Conditions
Electrostatic Discharge - Charged Device Model (ESD-CDM)	1	12	12	0 fails at Room and Hot
Electrostatic Discharge - Latch-up (ESD-LU)	1	6	6	0 fails at Room and Hot
Electrical Distribution (ED)	3	30	90	-